- **Count Divider Chain**
- **Digitally Programmable from 2^2 to 2^n (n = 31 for 'LS292, n = 15 for 'LS294)**
- **Useable Frequency Range from DC to 30 MHz**
- **Easily Expandable**
- **Applications**
  - **Frequency Division**
  - **Digital Timing**

description

These programmable frequency dividers/digital timers contain 31 flip-flops plus 30 gates ('LS292) or 15 flip-flops plus 29 gates ('LS294) on a single chip. The count modulo is under digital control of the inputs provided.

Both types feature an active-low clear input to initialize the state of all flip-flops. To facilitate incoming inspection, test points are provided (TP1, TP2, and TP3 on the 'LS292 and TP on the 'LS294). These test points are not intended to drive system loads. Both types feature two clock inputs; either one may be used for clock gating. (See the function table below.)

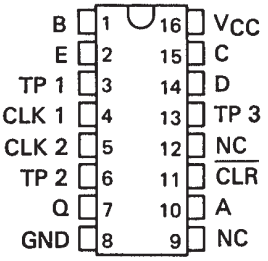
A brief look at the digital timing capabilities of the 'LS292 will show that with a 1-MHz input frequency, programming for 2^{10} will give a period of 1.024 ms, and 2^{20} will give a period of 1.05 sec, 2^{26} will give a period of 1.12 min, and 2^{31} will give a period of 35.79 min.

These devices are easily cascadable giving limitless possibilities to timing delays that can be achieved.

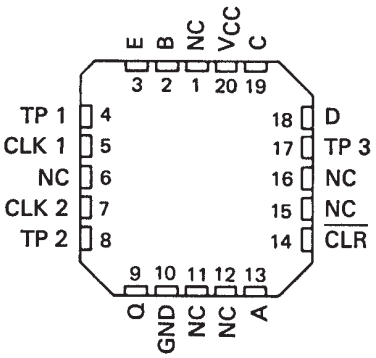
FUNCTION TABLE

CLEAR	CLK 1	CLK 2	Q OUTPUT MODE
L	X	X	Cleared to L
H	↑	L	Count
H	L	↑	Count
H	H	X	Inhibit
H	X	H	Inhibit

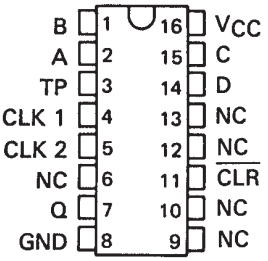
SN54LS292 . . . J OR W PACKAGE
SN74LS292 . . . N PACKAGE
(TOP VIEW)



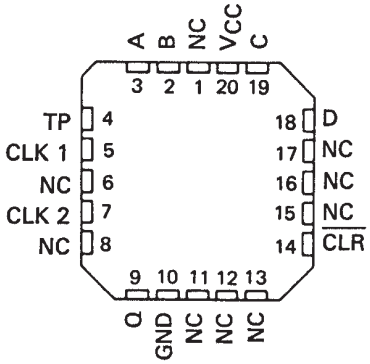
SN54LS292 . . . FK PACKAGE
(TOP VIEW)



SN54LS294 . . . J OR W PACKAGE
SN74LS294 . . . N PACKAGE
(TOP VIEW)

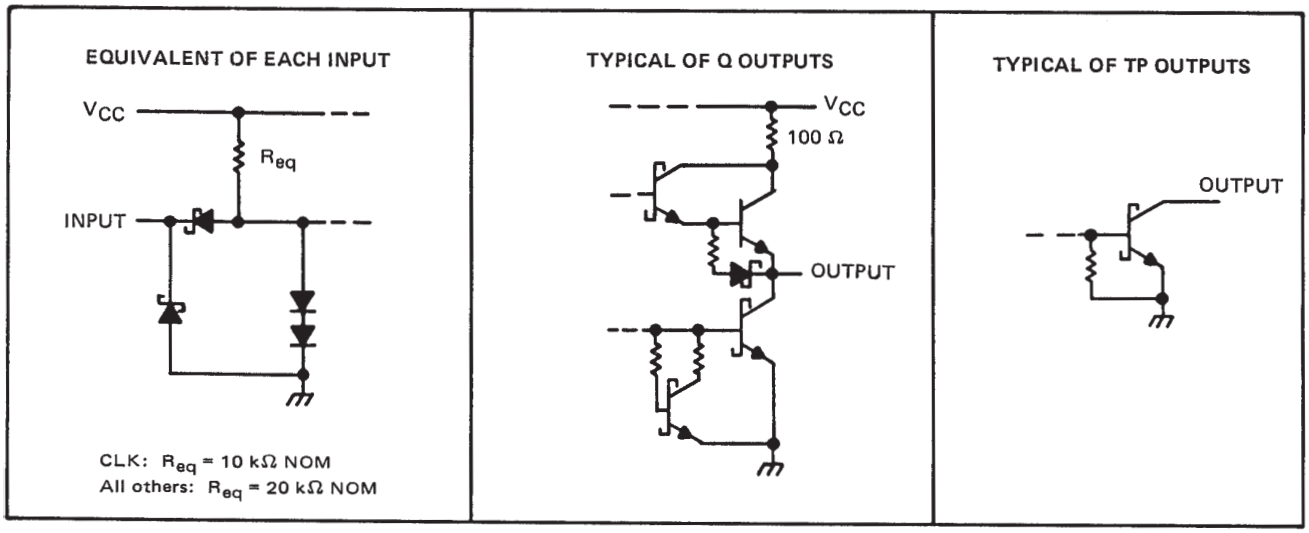


SN54LS294 . . . FK PACKAGE
(TOP VIEW)



NC — No internal connection.

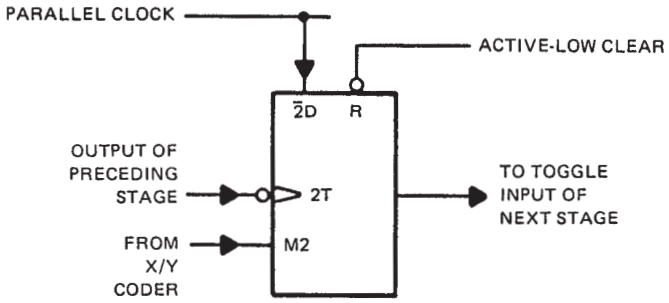
schematics of inputs and outputs



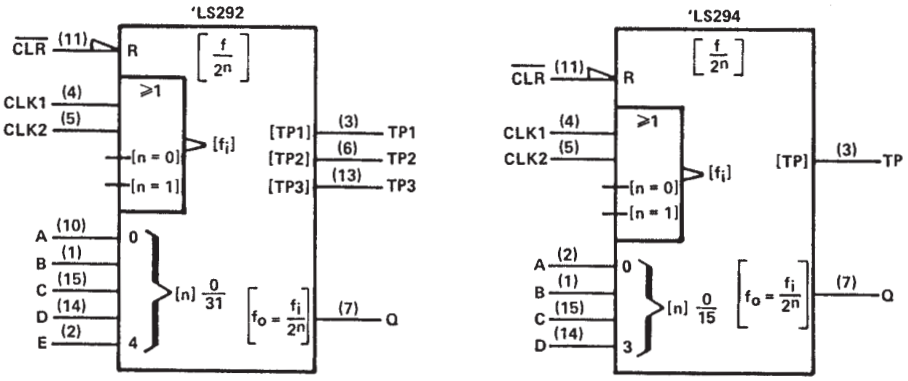
operation

The functional block diagram shows that the count modulo is controlled by an X/Y decoder connected to the mode control inputs of several flip-flops. These flip flops with mode controls each have a "D" input connected to the parallel clock line and a "T" input driven by the preceding stage. The parallel clock frequency is always the input frequency divided by four.

The X/Y decoder output selected by the programming inputs goes low. While a mode control is low, the "D" input of that flip-flop is enabled, and the signal from the parallel clock line ($f_{in} \div 4$) is passed to the "T" input of the following stage. All the other mode controls are high enabling the "T" inputs and causing each flip-flop in turn to divide by two.



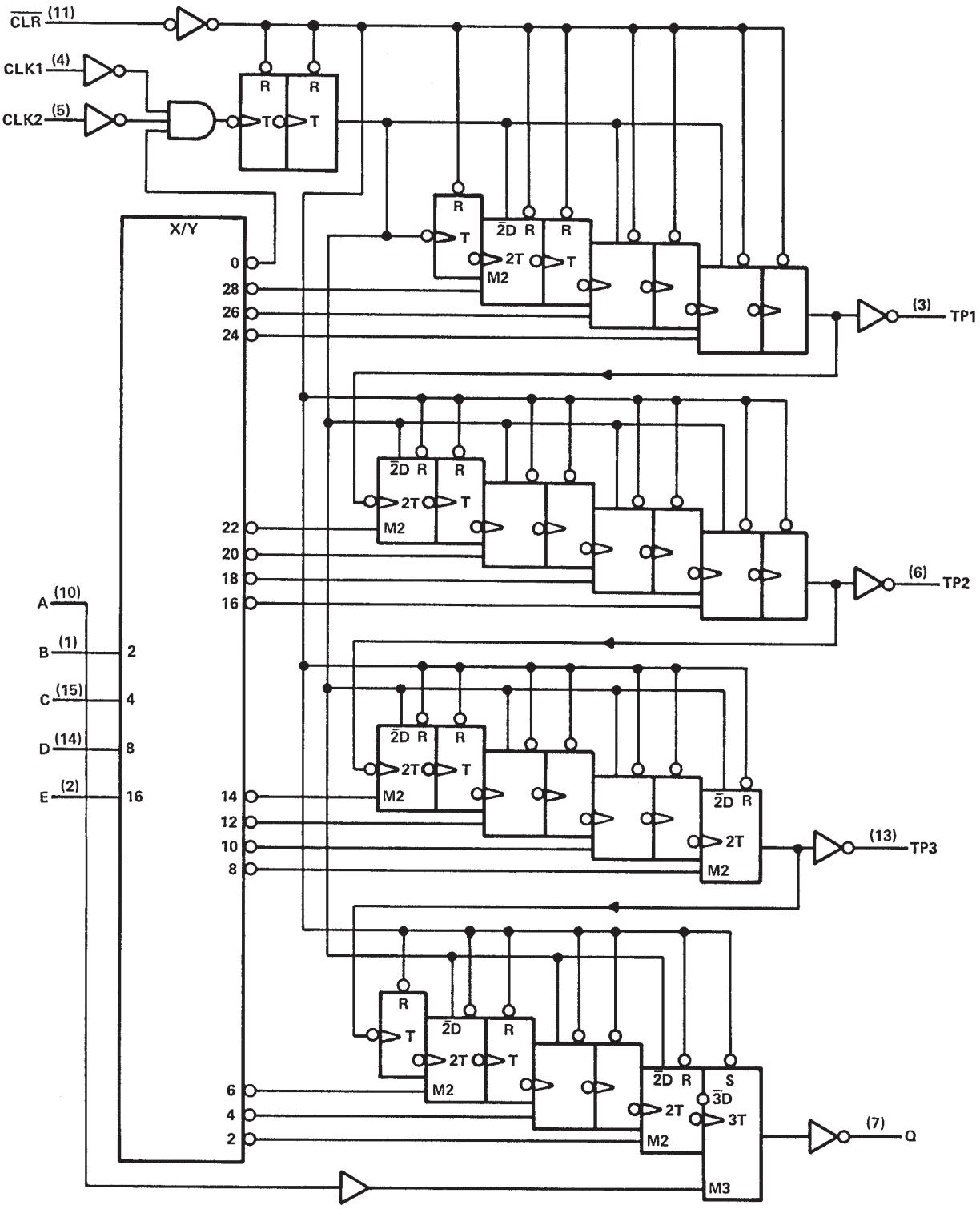
logic symbols†



†These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for J, N, and W packages.

logic diagram (positive logic)

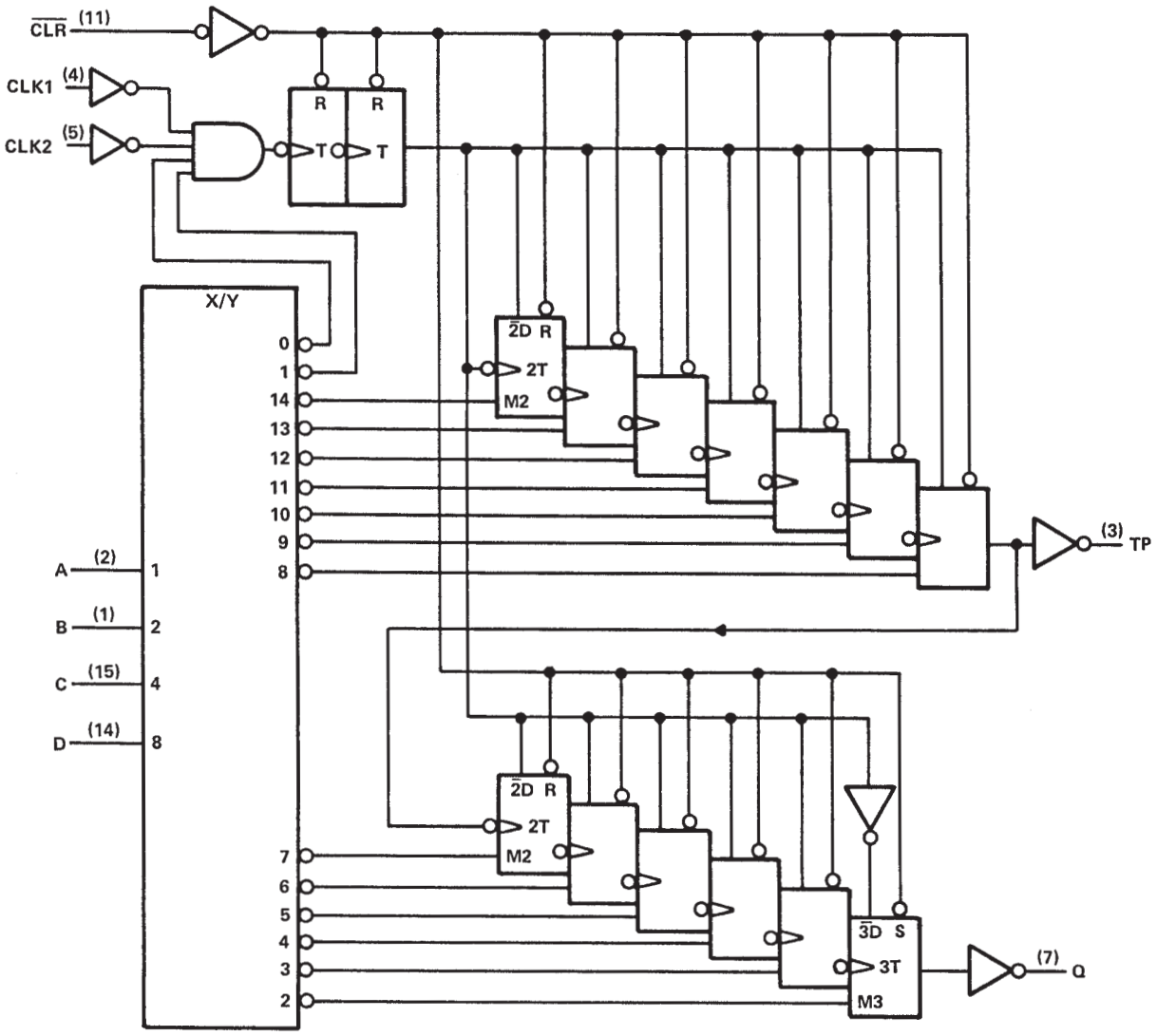
'LS292



Pin numbers shown are for J, N, and W packages.

logic diagram (positive logic)

'LS294



Pin numbers shown are for J, N, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 7 V
Operating free-air temperature range: SN54LS292, SN54LS294 . . . . . –55°C to 125°C
SN74LS292, SN74LS294 . . . . . 0°C to 70°C
Storage temperature range . . . . . –65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

			SN54LS'			SN74LS'			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.7			0.8	V
I_{OH}	High-level output current (Q only)				−1.2			−1.2	mA
I_{OL}	Low-level output current (Q only)				12			24	mA
f_{clock}	Clock frequency		0		30	0		30	MHz
t_w	Duration of clock input pulse		16			16			ns
t_w	Duration of clear pulse	'LS292	55			55			ns
		'LS294	35			35			
t_{su}	Clear inactive-state setup time		15			15			ns
T_A	Operating free-air temperature		−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN54LS'			SN74LS'			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}		V_{CC} = MIN, I_I = −18 mA				−1.5			−1.5	V
V_{OH}	Q	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX	I_{OH} = −1.2 mA,	2.4	3.4		2.4	3.4		V
V_{OL}	Q	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX	I_{OL} = 12 mA		0.25	0.4		0.25	0.4	V
	TP¶		I_{OL} = 24 mA					0.35	0.5	
			I_{OL} = 0.5 mA					0.25	0.4	
I_I		V_{CC} = MAX, V_I = 7 V				0.1			0.1	mA
I_{IH}		V_{CC} = MAX, V_I = 2.7 V				20			20	μA
I_{IL}	CLK1, CLK2	V_{CC} = MAX, V_I = 0.4 V				−0.8			−0.8	mA
	All others					−0.4			−0.4	
I_{OS}§	Q	V_{CC} = MAX		−30		−130	−30		−130	mA
I_{CC}	'LS292	V_{CC} = MAX, All inputs grounded, All outputs open			40	75		40	75	mA
	'LS294				30	50		30	50	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ The duration of the short-circuit should not exceed one second.
¶ The TP output or outputs are not intended to drive external loads but are solely provided for test points.

switching characteristics, V_{CC} = 5 V, T_A = 25°C, R_L = 667 Ω, C_L = 45 pF (see Figure 1)

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS292			'LS294			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
f_{max}	CLK1 or 2			30	50		30	50		MHz
t_{PLH}		Q	Modulo set at 22, A thru E = LLLHL ('LS292) A thru D = LLHL ('LS294)		55	90		55	90	ns
t_{PHL}		Q			80	120		80	120	ns
t_{PHL}	$\overline{CLR}$	Q			85	130		35	65	ns

†f_{MAX} = maximum clock frequency
t_{PLH} = Propagation delay time, low-to-high-level output
t_{PHL} = Propagation delay time, high-to-low-level output
NOTE 2: Load circuits and voltage waveforms are shown in Section 1. To be used on TP outputs only.

'LS292 FUNCTION TABLE

PROGRAMMING INPUTS					FREQUENCY DIVISION							
					Q		TP1		TP2		TP3	
E	D	C	B	A	BINARY	DECIMAL	BINARY	DECIMAL	BINARY	DECIMAL	BINARY	DECIMAL
L	L	L	L	L	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit
L	L	L	L	H	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit
L	L	L	H	L	2^2	4	2^9	512	2^{17}	131,072	2^{24}	16,777,216
L	L	L	H	H	2^3	8	2^9	512	2^{17}	131,072	2^{24}	16,777,216
L	L	H	L	L	2^4	16	2^9	512	2^{17}	131,072	2^{24}	16,777,216
L	L	H	L	H	2^5	32	2^9	512	2^{17}	131,072	2^{24}	16,777,216
L	L	H	H	L	2^6	64	2^9	512	2^{17}	131,072	2^{24}	16,777,216
L	L	H	H	H	2^7	128	2^9	512	2^{17}	131,072	2^{24}	16,777,216
L	H	L	L	L	2^8	256	2^9	512	2^{17}	131,072	2^2	4
L	H	L	L	H	2^9	512	2^9	512	2^{17}	131,072	2^2	4
L	H	L	H	L	2^{10}	1,024	2^9	512	2^{17}	131,072	2^4	16
L	H	L	H	H	2^{11}	2,048	2^9	512	2^{17}	131,072	2^4	16
L	H	H	L	L	2^{12}	4,096	2^9	512	2^{17}	131,072	2^6	64
L	H	H	L	H	2^{13}	8,192	2^9	512	2^{17}	131,072	2^6	64
L	H	H	H	L	2^{14}	16,384	2^9	512	Disabled Low		2^8	256
L	H	H	H	H	2^{15}	32,768	2^9	512	Disabled Low		2^8	256
H	L	L	L	L	2^{16}	65,536	2^9	512	2^3	8	2^{10}	1,024
H	L	L	L	H	2^{17}	131,072	2^9	512	2^3	8	2^{10}	1,024
H	L	L	H	L	2^{18}	262,144	2^9	512	2^5	32	2^{12}	4,096
H	L	L	H	H	2^{19}	524,288	2^9	512	2^5	32	2^{12}	4,096
H	L	H	L	L	2^{20}	1,048,576	2^9	512	2^7	128	2^{14}	16,384
H	L	H	L	H	2^{21}	2,097,152	2^9	512	2^7	128	2^{14}	16,384
H	L	H	H	L	2^{22}	4,194,304	Disabled Low		2^9	512	2^{16}	65,536
H	L	H	H	H	2^{23}	8,388,608	Disabled Low		2^9	512	2^{16}	65,536
H	H	L	L	L	2^{24}	16,777,216	2^3	8	2^{11}	2,048	2^{18}	262,144
H	H	L	L	H	2^{25}	33,554,432	2^3	8	2^{11}	2,048	2^{18}	262,144
H	H	L	H	L	2^{26}	67,108,864	2^5	32	2^{13}	8,192	2^{20}	1,048,576
H	H	L	H	H	2^{27}	134,217,728	2^5	32	2^{13}	8,192	2^{20}	1,048,576
H	H	H	L	L	2^{28}	268,435,456	2^7	128	2^{15}	32,768	2^{22}	4,194,304
H	H	H	L	H	2^{29}	536,870,912	2^7	128	2^{15}	32,768	2^{22}	4,194,304
H	H	H	H	L	2^{30}	1,073,741,824	2^9	512	2^{17}	131,072	2^{24}	16,777,216
H	H	H	H	H	2^{31}	2,147,483,648	2^9	512	2^{17}	131,072	2^{24}	16,777,216

'LS294 FUNCTION TABLE

PROGRAMMING INPUTS				FREQUENCY DIVISION			
				Q		TP	
D	C	B	A	BINARY	DECIMAL	BINARY	DECIMAL
L	L	L	L	Inhibit	Inhibit	Inhibit	Inhibit
L	L	L	H	Inhibit	Inhibit	Inhibit	Inhibit
L	L	H	L	2^2	4	2^9	512
L	L	H	H	2^3	8	2^9	512
L	H	L	L	2^4	16	2^9	512
L	H	L	H	2^5	32	2^9	512
L	H	H	L	2^6	64	2^9	512
L	H	H	H	2^7	128	Disabled Low	
H	L	L	L	2^8	256	2^2	4
H	L	L	H	2^9	512	2^3	8
H	L	H	L	2^{10}	1,024	2^4	16
H	L	H	H	2^{11}	2,048	2^5	32
H	H	L	L	2^{12}	4,096	2^6	64
H	H	L	H	2^{13}	8,192	2^7	128
H	H	H	L	2^{14}	16,384	2^8	256
H	H	H	H	2^{15}	32,768	2^9	512

switching loads

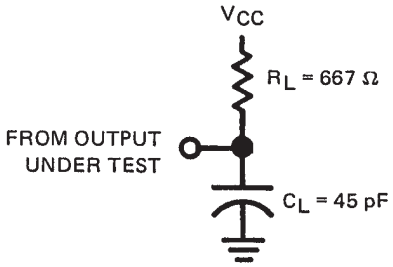
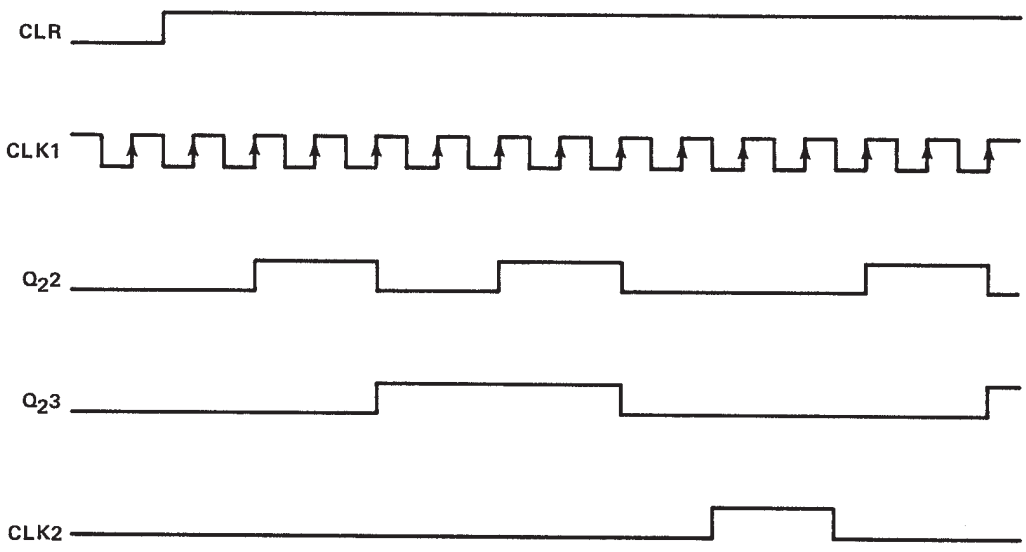


FIGURE 1

'LS292 and 'LS294 timing diagram



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Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
Low Power Wireless	www.ti.com/lpw	Telephony	www.ti.com/telephony
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Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
Low Power Wireless	www.ti.com/lpw	Telephony	www.ti.com/telephony
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Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
Low Power Wireless	www.ti.com/lpw	Telephony	www.ti.com/telephony
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Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
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PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN74LS292N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS292N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS292N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
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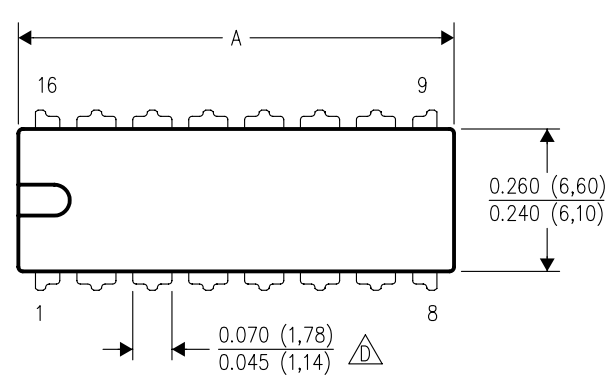
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
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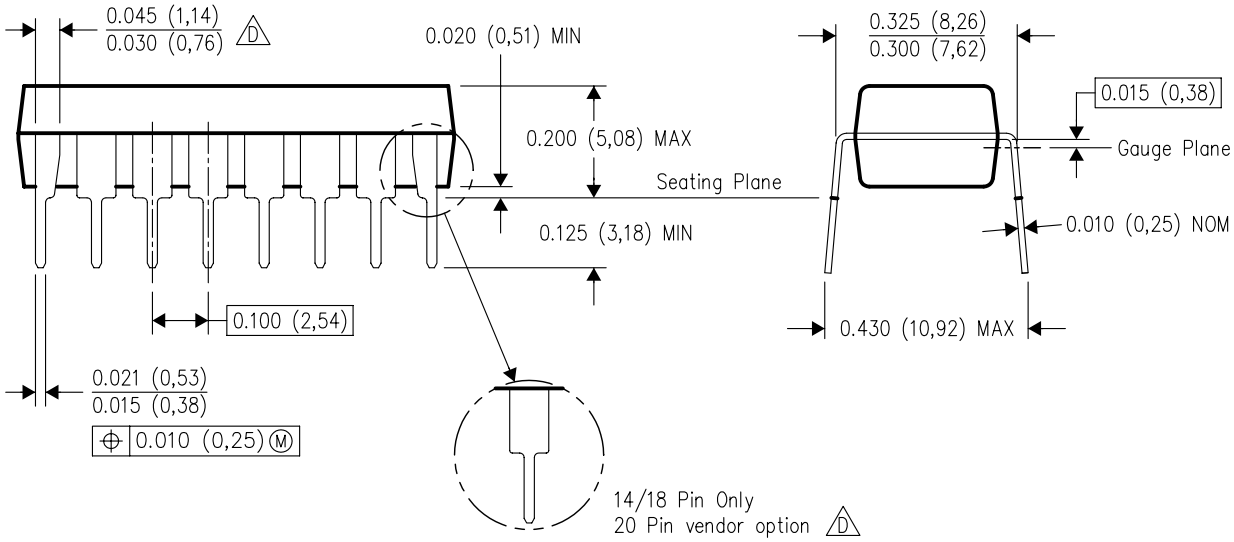
MS–001 VARIATION (C)	AA	BB	AC	AD



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SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
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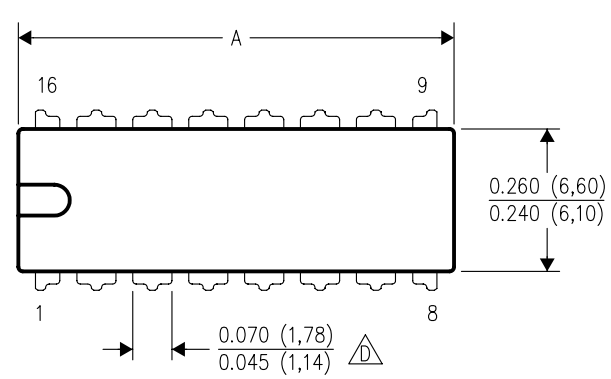

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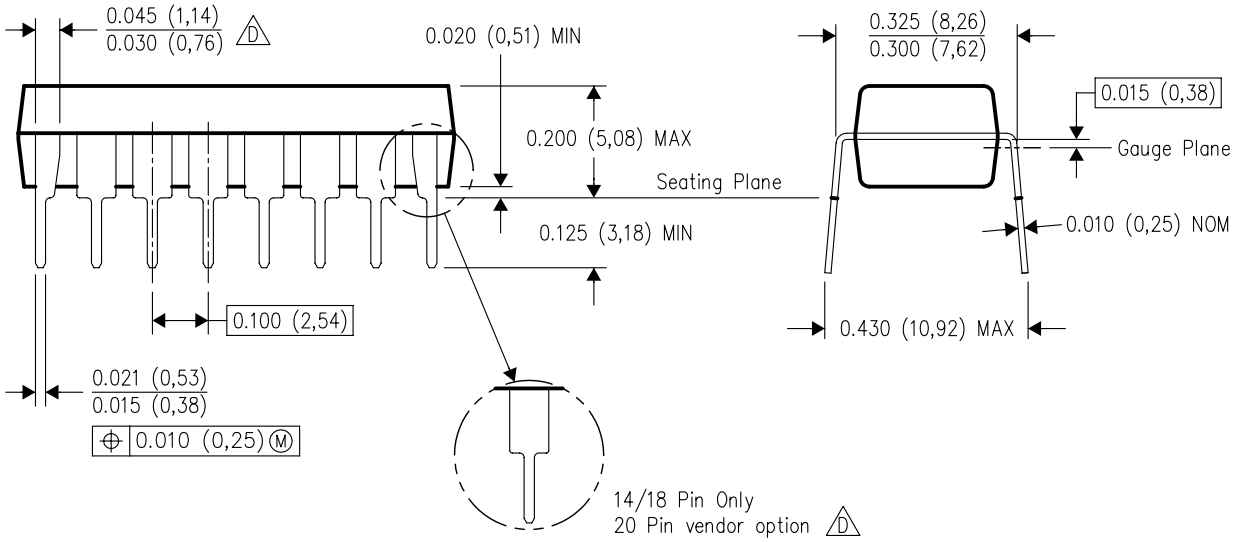

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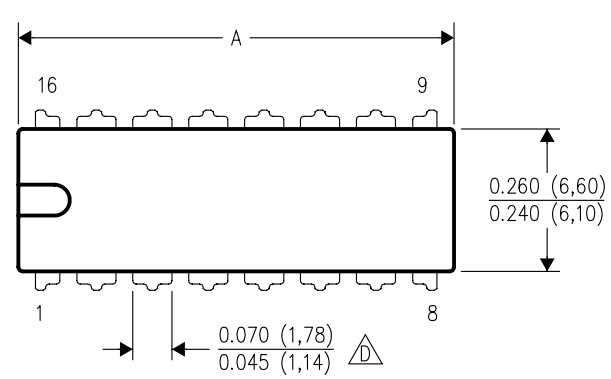

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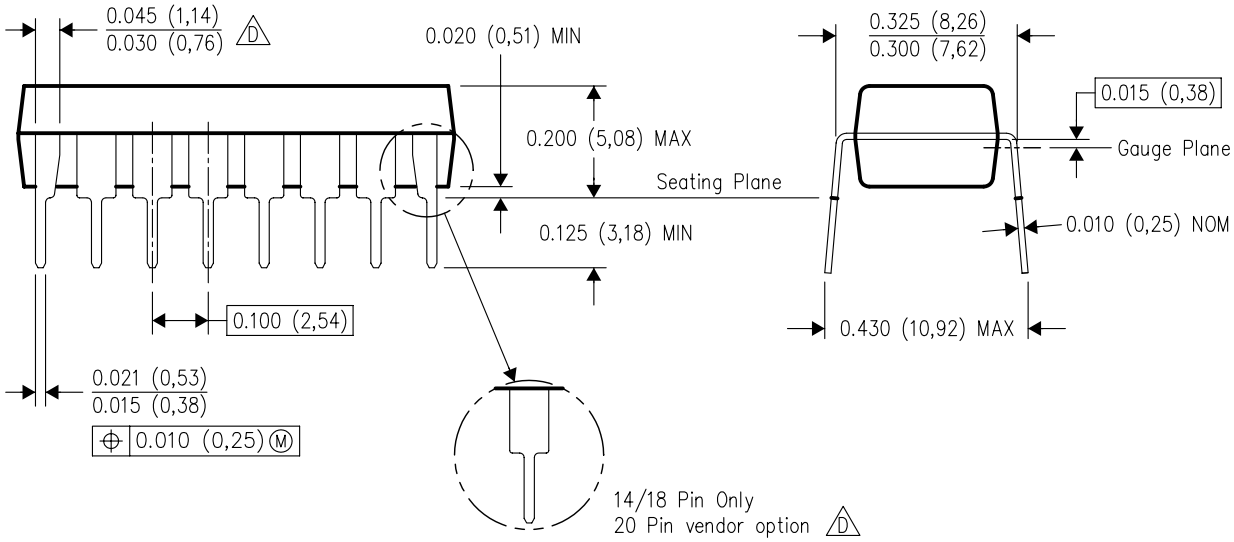

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SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

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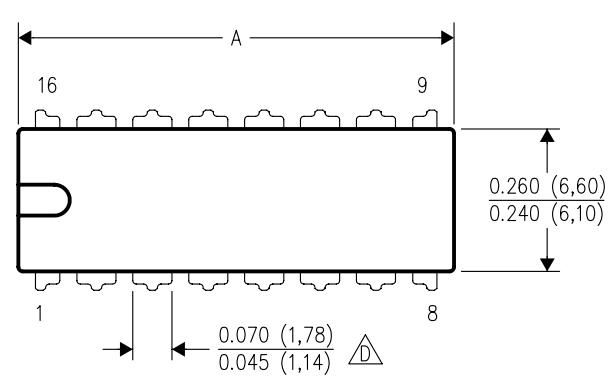
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

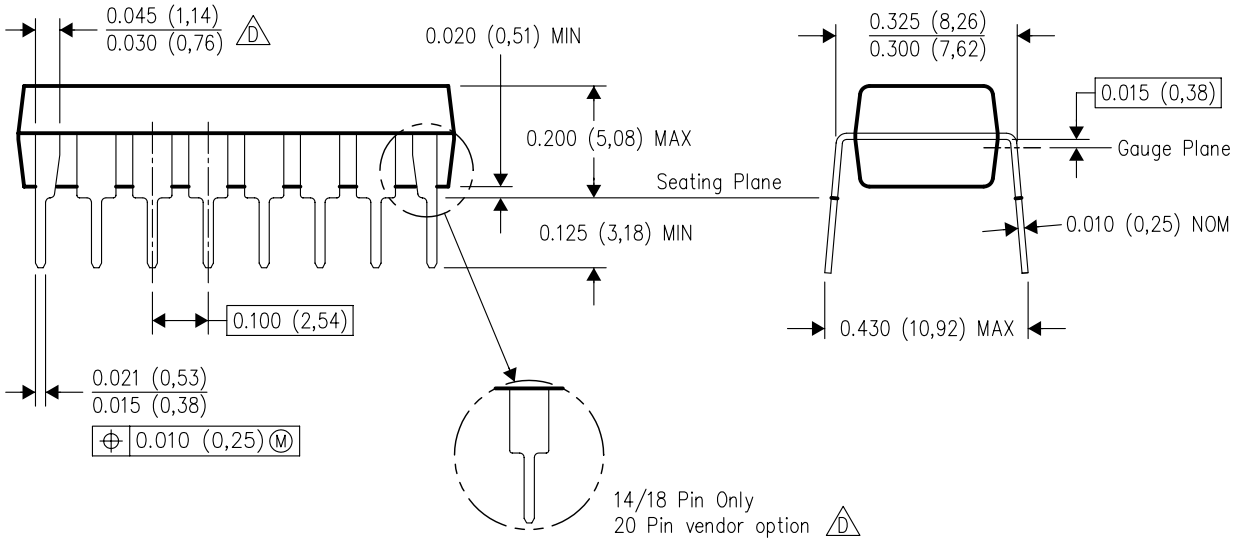
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

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D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN74LS292N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS292N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS292N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

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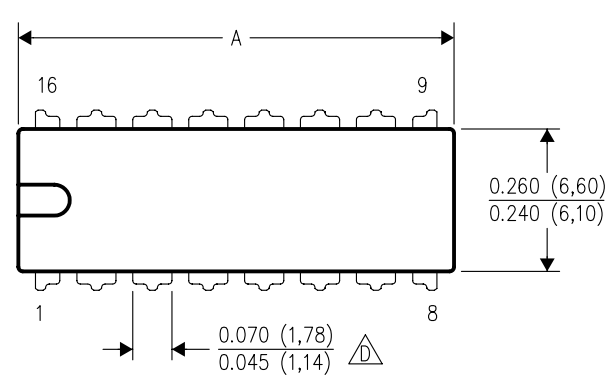
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
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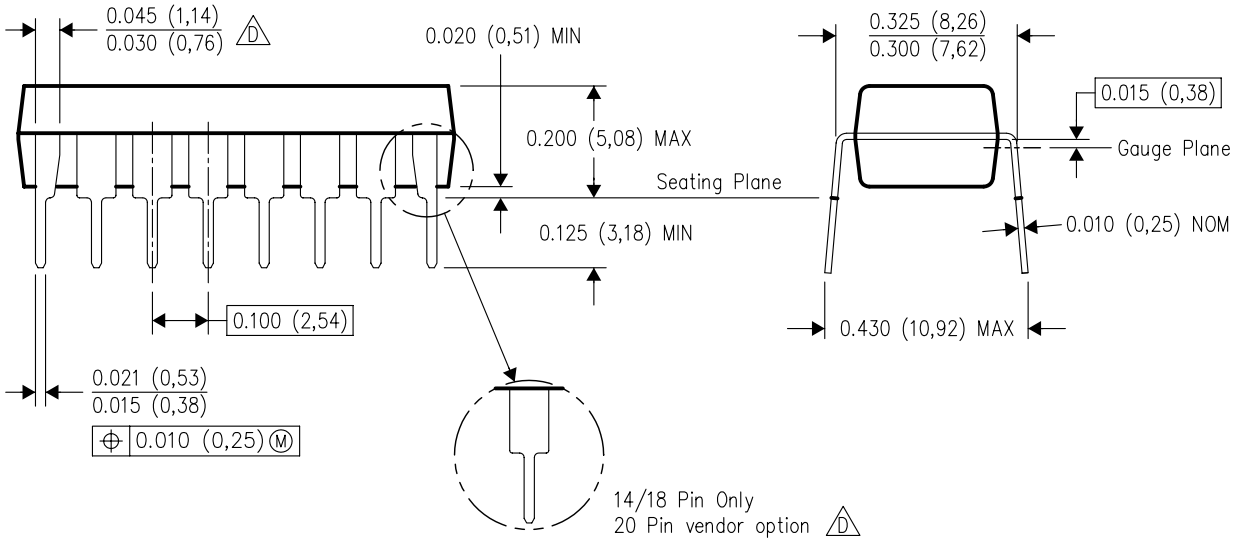

4040049/E 12/2002

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SN74LS292N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

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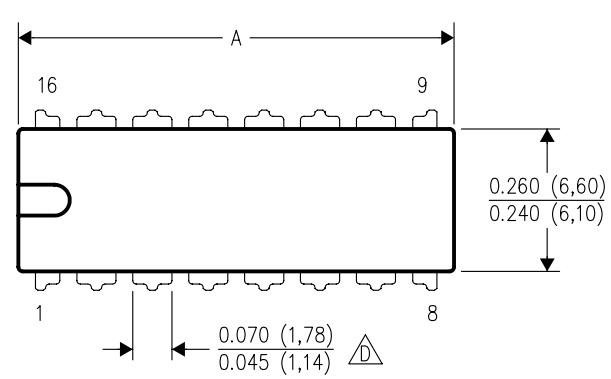
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



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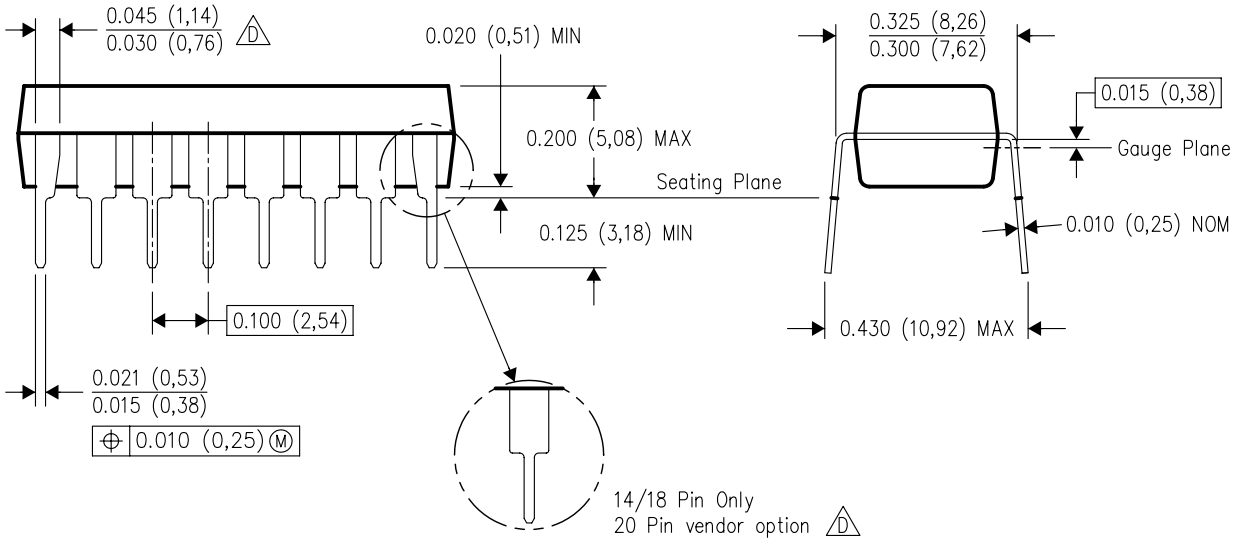

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SN74LS292N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

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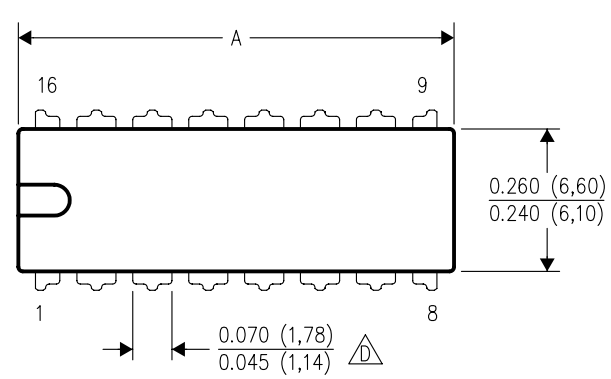
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



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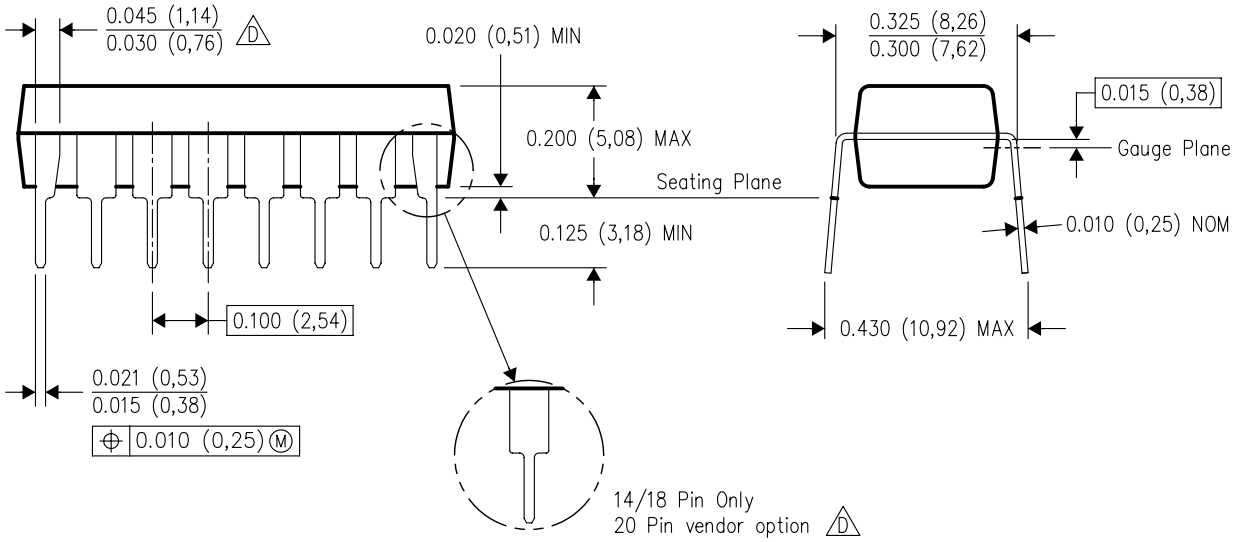

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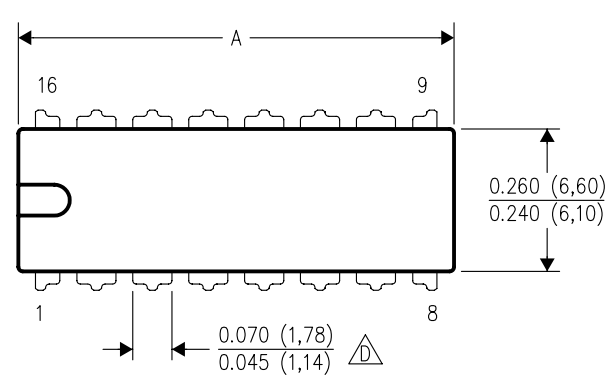
PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



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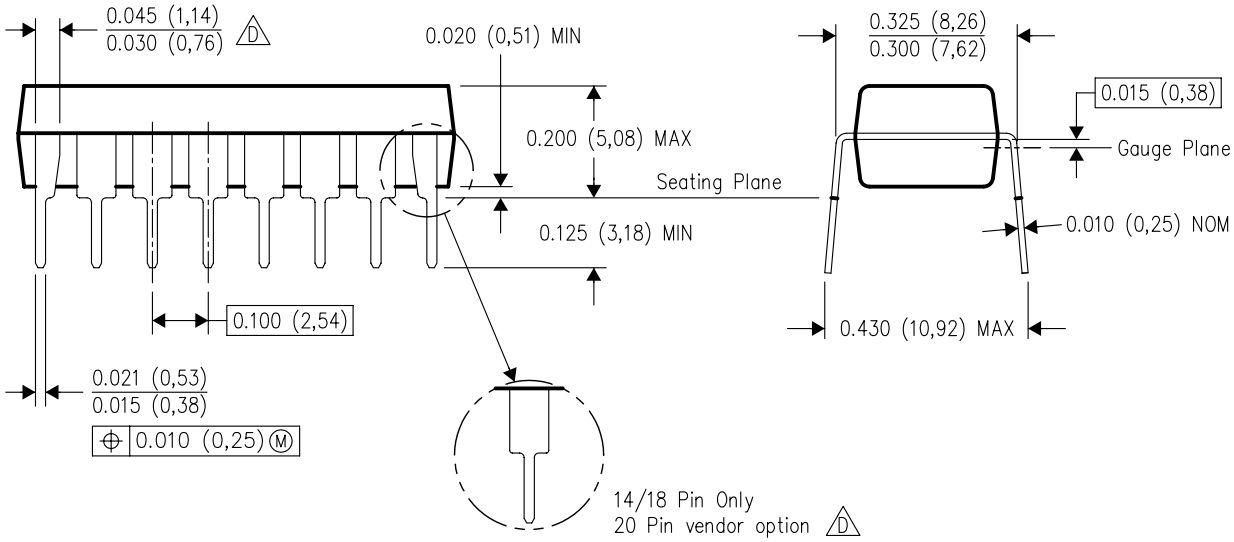

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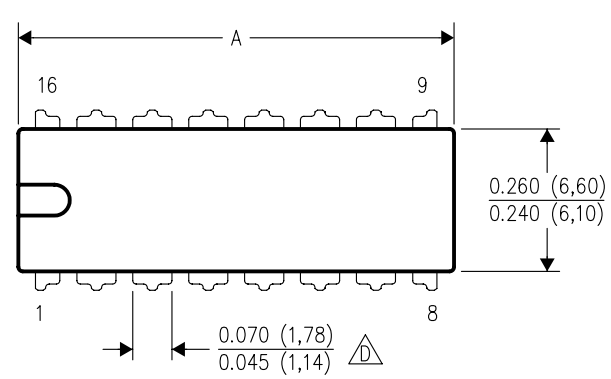
16 PINS SHOWN



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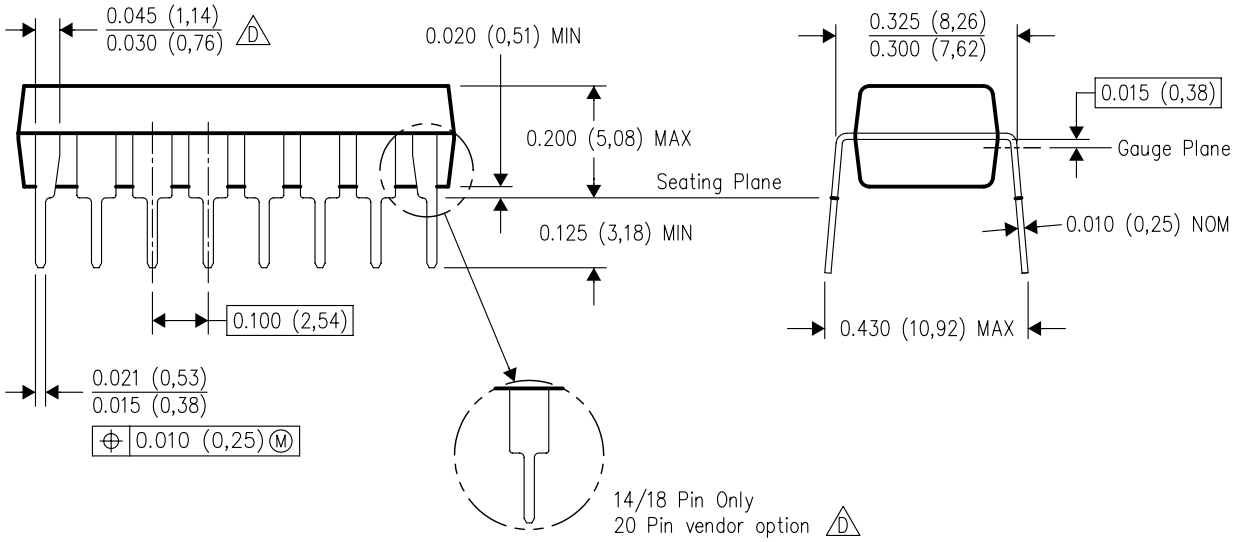

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SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

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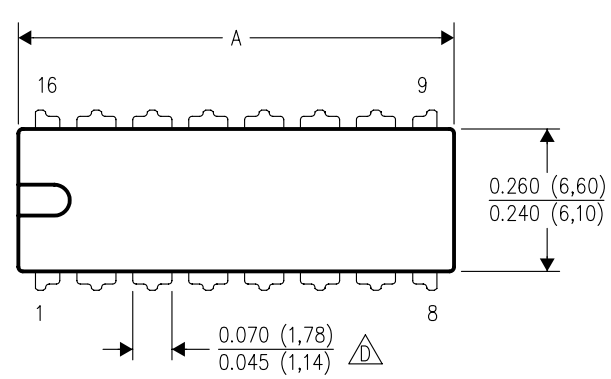
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

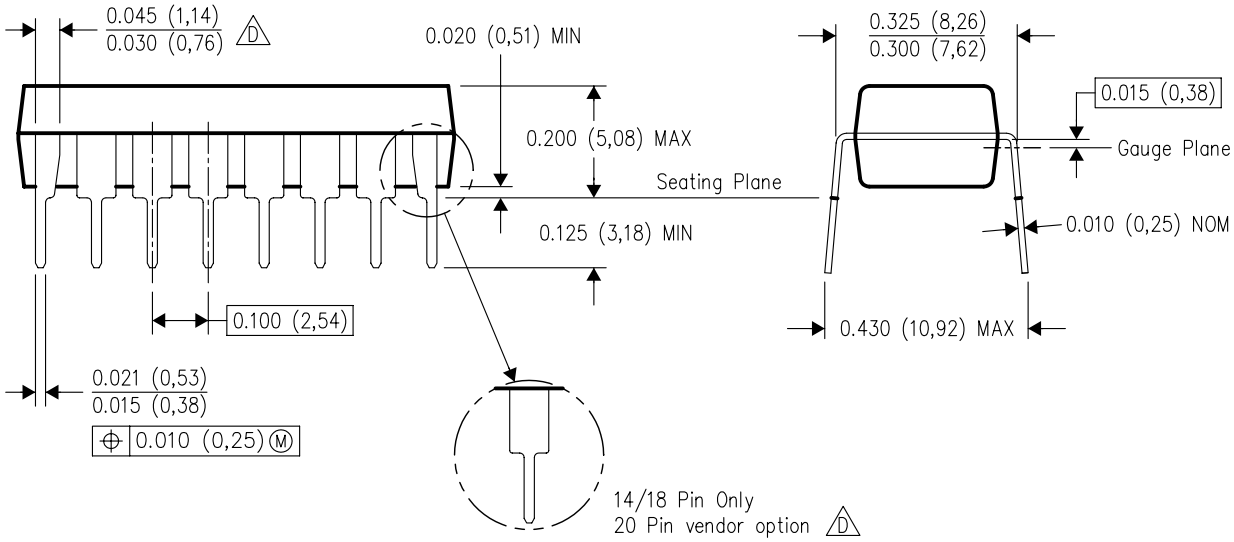
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

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D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN74LS292N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS292N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS292N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

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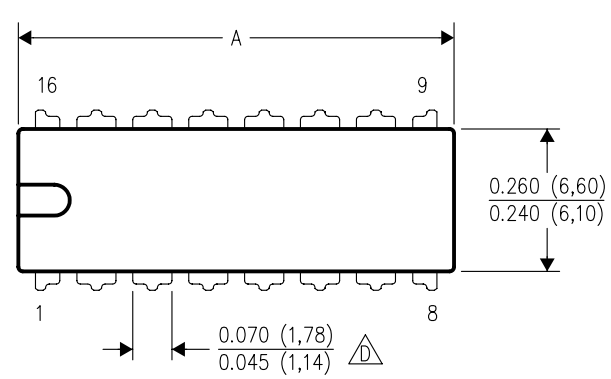
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
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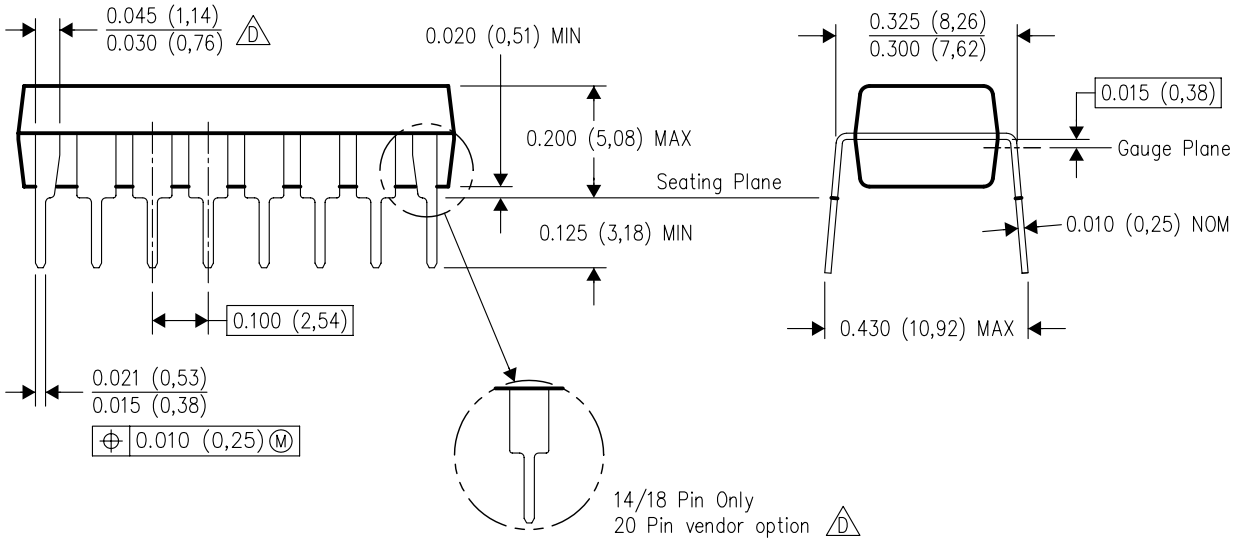
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

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SN74LS292N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS292N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

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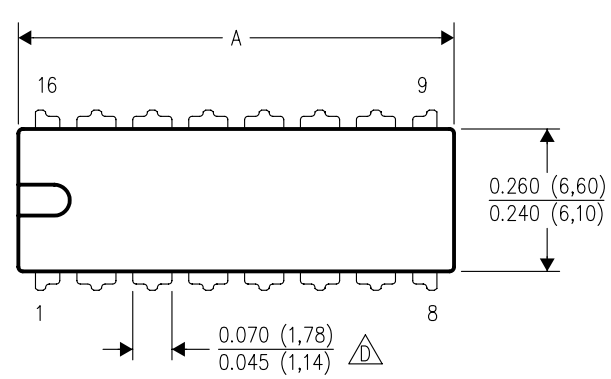
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



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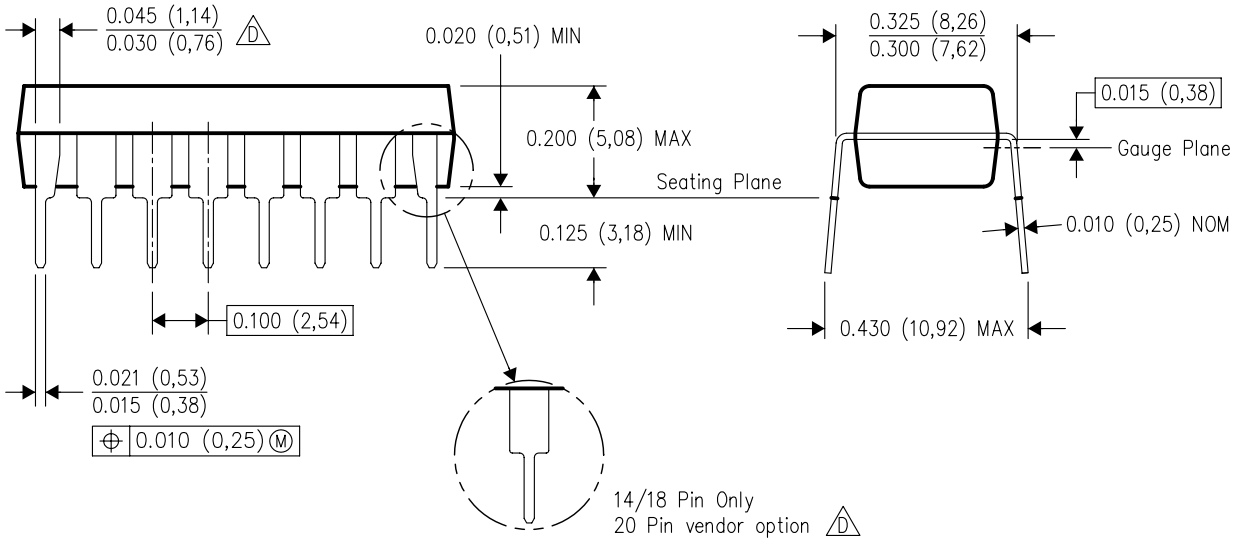
MS–001 VARIATION (C)	AA	BB	AC	AD



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SN74LS292N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

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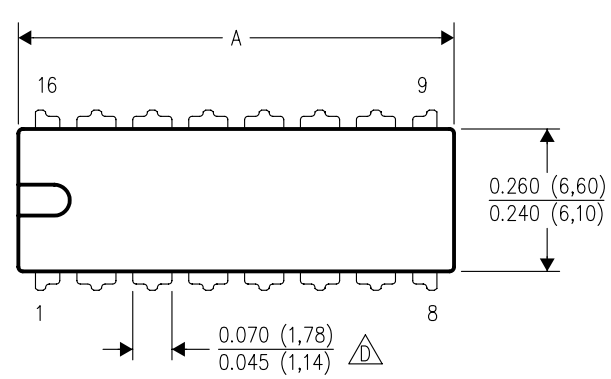
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



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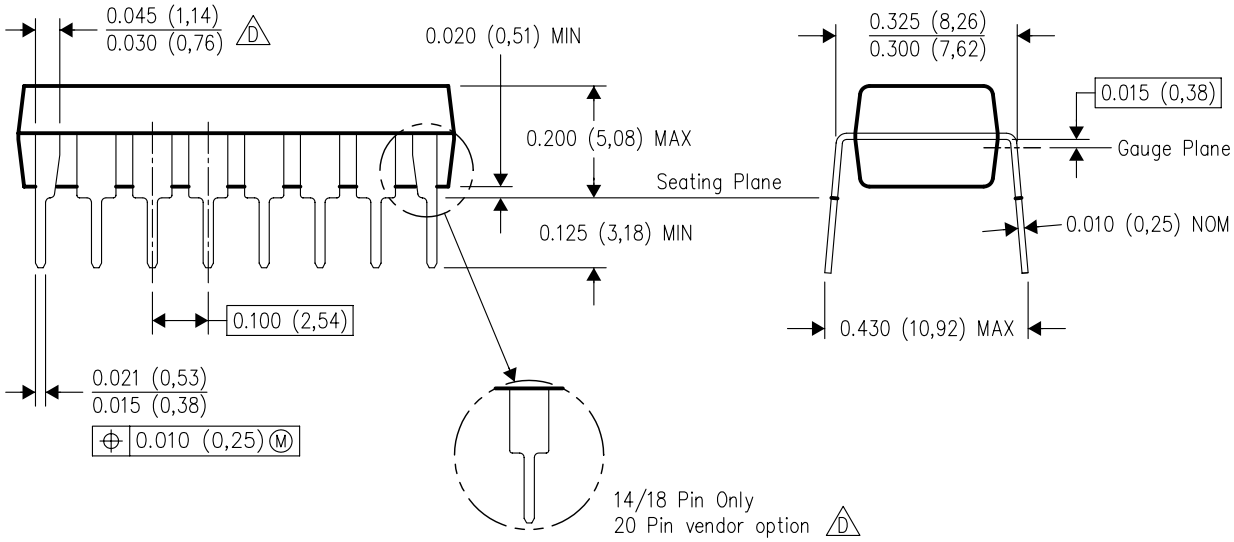

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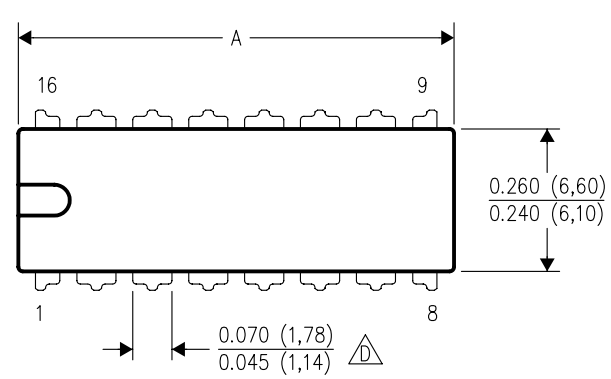
PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



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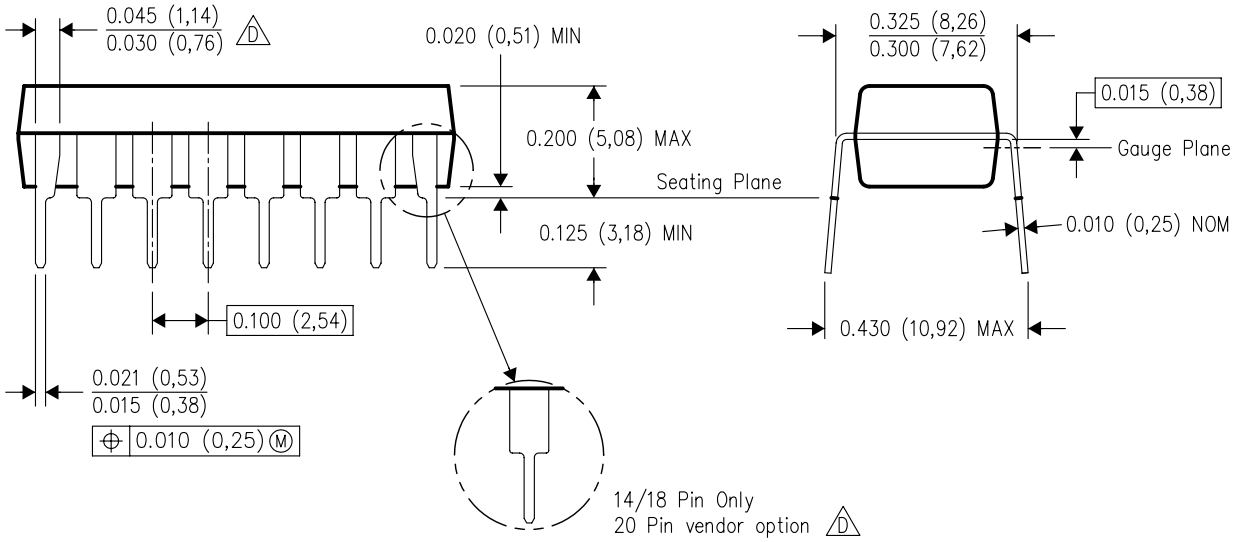

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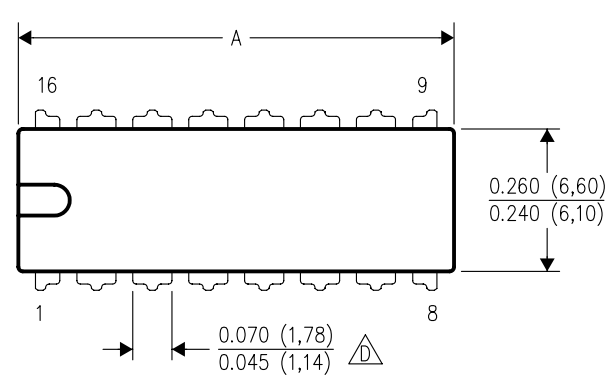
16 PINS SHOWN



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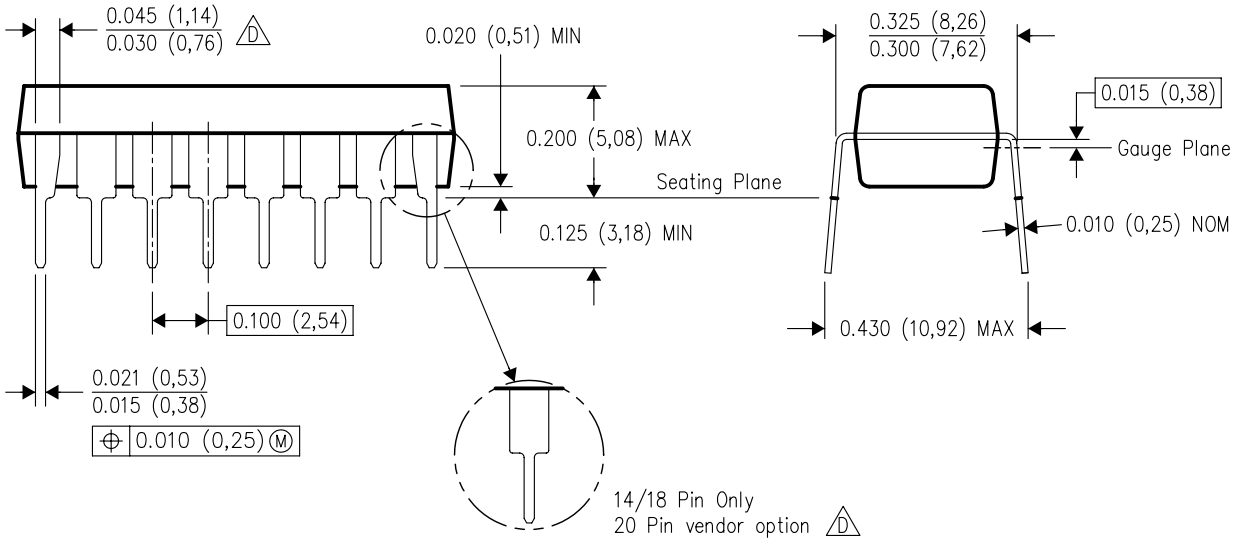

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SN74LS292N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS292N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

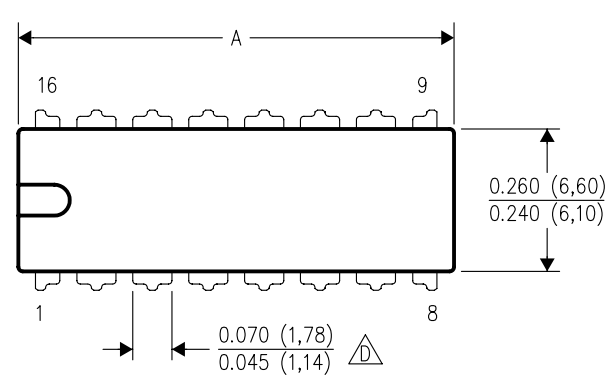
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

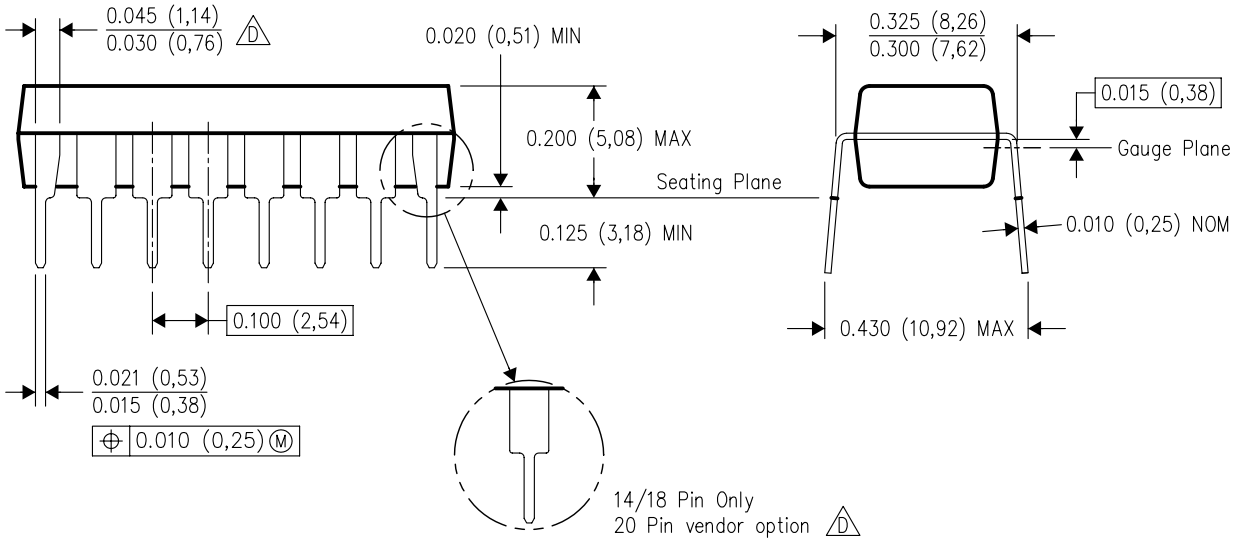
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN74LS292N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS292N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS292N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS292NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS294NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

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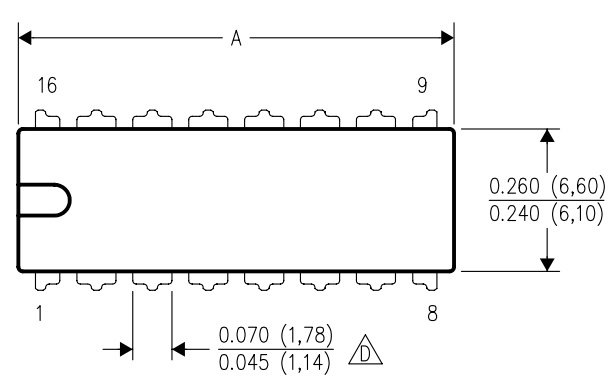
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



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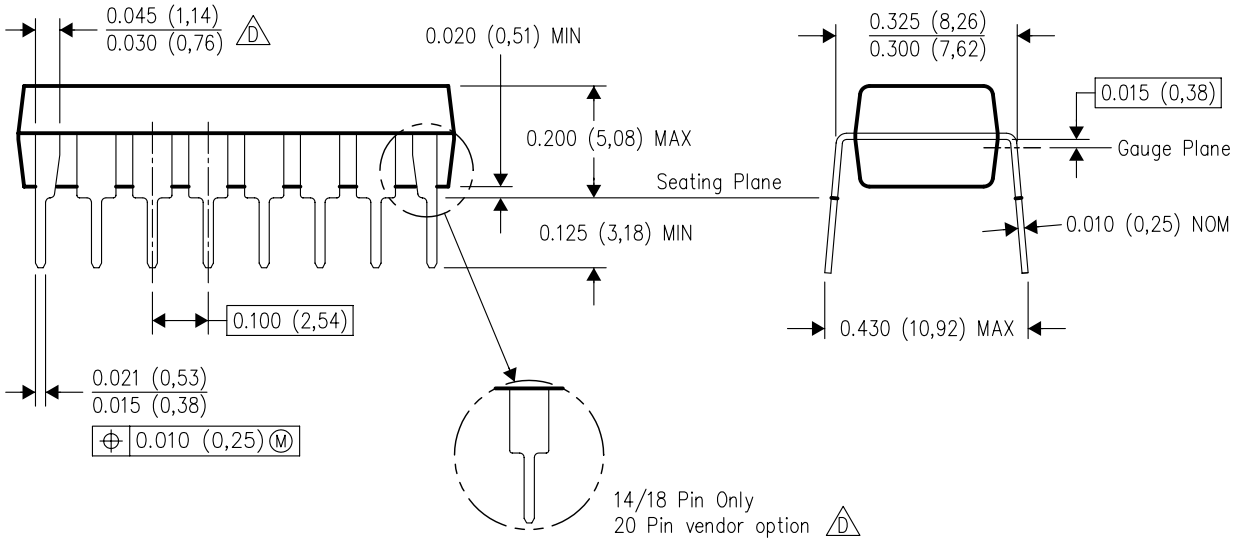
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
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